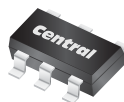
Material Composition Specification

SOT-26 Case



Device average mass . . . . 15.8 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.54%	0.24	Si	7440-21-3	1.54%	0.243	15,381
bond wire	gold	0.06%	0.01	Au	7440-57-5	0.06%	0.009	570
leadframe	copper w/ silver plating	40.4%	6.38	Cu	7440-50-8	39.91%	6.305	399,076
				Ag	7440-22-4	0.49%	0.078	4,937
encapsulation*	EMC	53.67%	8.48	silica	7631-86-9	39.71%	6.273	397,050
				epoxy resin	Proprietary	12.49%	1.973	124,881
				Sb_2O_3	1309-64-4	1.08%	0.17	10,760
				TBBA	79-94-7	0.27%	0.043	2,722
				carbon	1333-86-4	0.13%	0.021	1,329
	EMC GREEN	53.67%	8.48	silica	60676-86-0	35.88%	5.668	358,756
				epoxy resin	29690-82-2	8.15%	1.287	81,485
				phenol resin	9003-35-4	4.09%	0.646	40,881
				carbon black	1333-86-4	0.28%	0.044	2,781
				metal hydroxide	1309-42-8	5.28%	0.835	52,840
plating**	tin/lead process	4.33%	0.68	Sn	7440-31-5	3.4%	0.537	33,989
				Pb	7439-92-1	0.94%	0.148	9,368
	matte tin	4.33%	0.68	Sn	7440-31-5	4.33%	0.684	43,294

*EMC GREEN molding compound is Halogen-Free.
**For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R7 (16-July 2018)